

Thyristor Module

V_{RRM} = 2x 1800 V

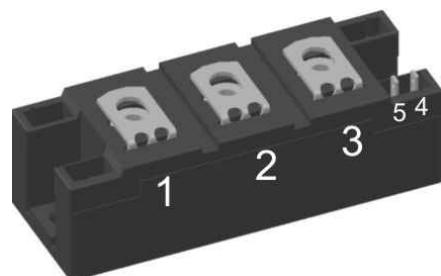
I_{TAV} = 181 A

V_T = 1.03 V

Phase leg

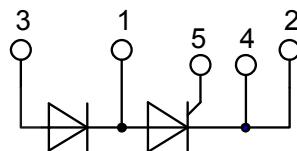
Part number

MCD162-18io1



Backside: isolated

 E72873



Features / Advantages:

- Thyristor for line frequency
- Planar passivated chip
- Long-term stability
- Direct Copper Bonded Al₂O₃-ceramic

Applications:

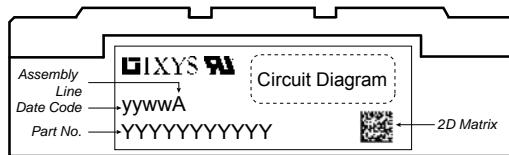
- Line rectifying 50/60 Hz
- Softstart AC motor control
- DC Motor control
- Power converter
- AC power control
- Lighting and temperature control

Package: Y4

- Isolation Voltage: 3600 V~
- Industry standard outline
- RoHS compliant
- Soldering pins for PCB mounting
- Base plate: DCB ceramic
- Reduced weight
- Advanced power cycling

Rectifier			Ratings			
Symbol	Definition	Conditions	min.	typ.	max.	Unit
$V_{RSM/DSM}$	max. non-repetitive reverse/forward blocking voltage	$T_{VJ} = 25^\circ C$			1900	V
$V_{RRM/DRM}$	max. repetitive reverse/forward blocking voltage	$T_{VJ} = 25^\circ C$			1800	V
I_{RD}	reverse current, drain current	$V_{RD} = 1800 V$	$T_{VJ} = 25^\circ C$		300	μA
		$V_{RD} = 1800 V$	$T_{VJ} = 125^\circ C$		10	mA
V_T	forward voltage drop	$I_T = 150 A$	$T_{VJ} = 25^\circ C$		1.09	V
		$I_T = 300 A$			1.25	V
		$I_T = 150 A$	$T_{VJ} = 125^\circ C$		1.03	V
		$I_T = 300 A$			1.25	V
I_{TAV}	average forward current	$T_C = 85^\circ C$	$T_{VJ} = 125^\circ C$		181	A
$I_{T(RMS)}$	RMS forward current	180° sine			300	A
V_{T0} r_T	threshold voltage slope resistance } for power loss calculation only		$T_{VJ} = 125^\circ C$		0.88	V
					1.15	$m\Omega$
R_{thJC}	thermal resistance junction to case				0.155	K/W
R_{thCH}	thermal resistance case to heatsink			0.07		K/W
P_{tot}	total power dissipation	$T_C = 25^\circ C$			645	W
I_{TSM}	max. forward surge current	$t = 10 \text{ ms}; (50 \text{ Hz}), \text{sine}$	$T_{VJ} = 45^\circ C$		6.00	kA
		$t = 8,3 \text{ ms}; (60 \text{ Hz}), \text{sine}$	$V_R = 0 V$		6.48	kA
		$t = 10 \text{ ms}; (50 \text{ Hz}), \text{sine}$	$T_{VJ} = 125^\circ C$		5.10	kA
		$t = 8,3 \text{ ms}; (60 \text{ Hz}), \text{sine}$	$V_R = 0 V$		5.51	kA
I^2t	value for fusing	$t = 10 \text{ ms}; (50 \text{ Hz}), \text{sine}$	$T_{VJ} = 45^\circ C$		180.0	kA^2s
		$t = 8,3 \text{ ms}; (60 \text{ Hz}), \text{sine}$	$V_R = 0 V$		174.7	kA^2s
		$t = 10 \text{ ms}; (50 \text{ Hz}), \text{sine}$	$T_{VJ} = 125^\circ C$		130.1	kA^2s
		$t = 8,3 \text{ ms}; (60 \text{ Hz}), \text{sine}$	$V_R = 0 V$		126.3	kA^2s
C_J	junction capacitance	$V_R = 400 V \ f = 1 \text{ MHz}$	$T_{VJ} = 25^\circ C$	273		pF
P_{GM}	max. gate power dissipation	$t_p = 30 \mu s$	$T_C = 125^\circ C$		120	W
		$t_p = 500 \mu s$			60	W
P_{GAV}	average gate power dissipation				8	W
$(di/dt)_{cr}$	critical rate of rise of current	$T_{VJ} = 125^\circ C; f = 50 \text{ Hz}$	repetitive, $I_T = 540 A$		150	$A/\mu s$
		$t_p = 200 \mu s; di_G/dt = 0.5 A/\mu s;$				
		$I_G = 0.5 A; V_D = \frac{2}{3} V_{DRM}$	non-repet., $I_T = 180 A$		500	$A/\mu s$
$(dv/dt)_{cr}$	critical rate of rise of voltage	$V_D = \frac{2}{3} V_{DRM}$	$T_{VJ} = 125^\circ C$		1000	$V/\mu s$
		$R_{GK} = \infty; \text{method 1 (linear voltage rise)}$				
V_{GT}	gate trigger voltage	$V_D = 6 V$	$T_{VJ} = 25^\circ C$		2.5	V
			$T_{VJ} = -40^\circ C$		2.6	V
I_{GT}	gate trigger current	$V_D = 6 V$	$T_{VJ} = 25^\circ C$		150	mA
			$T_{VJ} = -40^\circ C$		200	mA
V_{GD}	gate non-trigger voltage	$V_D = \frac{2}{3} V_{DRM}$	$T_{VJ} = 125^\circ C$		0.2	V
I_{GD}	gate non-trigger current				10	mA
I_L	latching current	$t_p = 30 \mu s$	$T_{VJ} = 25^\circ C$		300	mA
		$I_G = 0.5 A; di_G/dt = 0.5 A/\mu s$				
I_H	holding current	$V_D = 6 V \ R_{GK} = \infty$	$T_{VJ} = 25^\circ C$		200	mA
t_{gd}	gate controlled delay time	$V_D = \frac{1}{2} V_{DRM}$	$T_{VJ} = 25^\circ C$		2	μs
		$I_G = 0.5 A; di_G/dt = 0.5 A/\mu s$				
t_q	turn-off time	$V_R = 100 V; I_T = 300 A; V_D = \frac{2}{3} V_{DRM} \ T_{VJ} = 125^\circ C$	$di/dt = 10 A/\mu s; dv/dt = 20 V/\mu s; t_p = 200 \mu s$	150		μs

Package Y4			Ratings			
Symbol	Definition	Conditions	min.	typ.	max.	Unit
I_{RMS}	RMS current	per terminal			300	A
T_{VJ}	virtual junction temperature		-40		125	°C
T_{op}	operation temperature		-40		100	°C
T_{stg}	storage temperature		-40		125	°C
Weight				150		g
M_D	mounting torque		2.25		2.75	Nm
M_T	terminal torque		4.5		5.5	Nm
$d_{Spp/App}$	creepage distance on surface / striking distance through air		terminal to terminal	14.0	10.0	mm
$d_{Spb/Abp}$			terminal to backside	16.0	16.0	mm
V_{ISOL}	isolation voltage	t = 1 second t = 1 minute	50/60 Hz, RMS; $I_{ISOL} \leq 1$ mA		3600 3000	V V

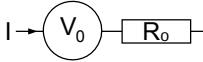


Ordering	Part Number	Marking on Product	Delivery Mode	Quantity	Code No.
Standard	MCD162-18io1	MCD162-18io1	Box	6	454508

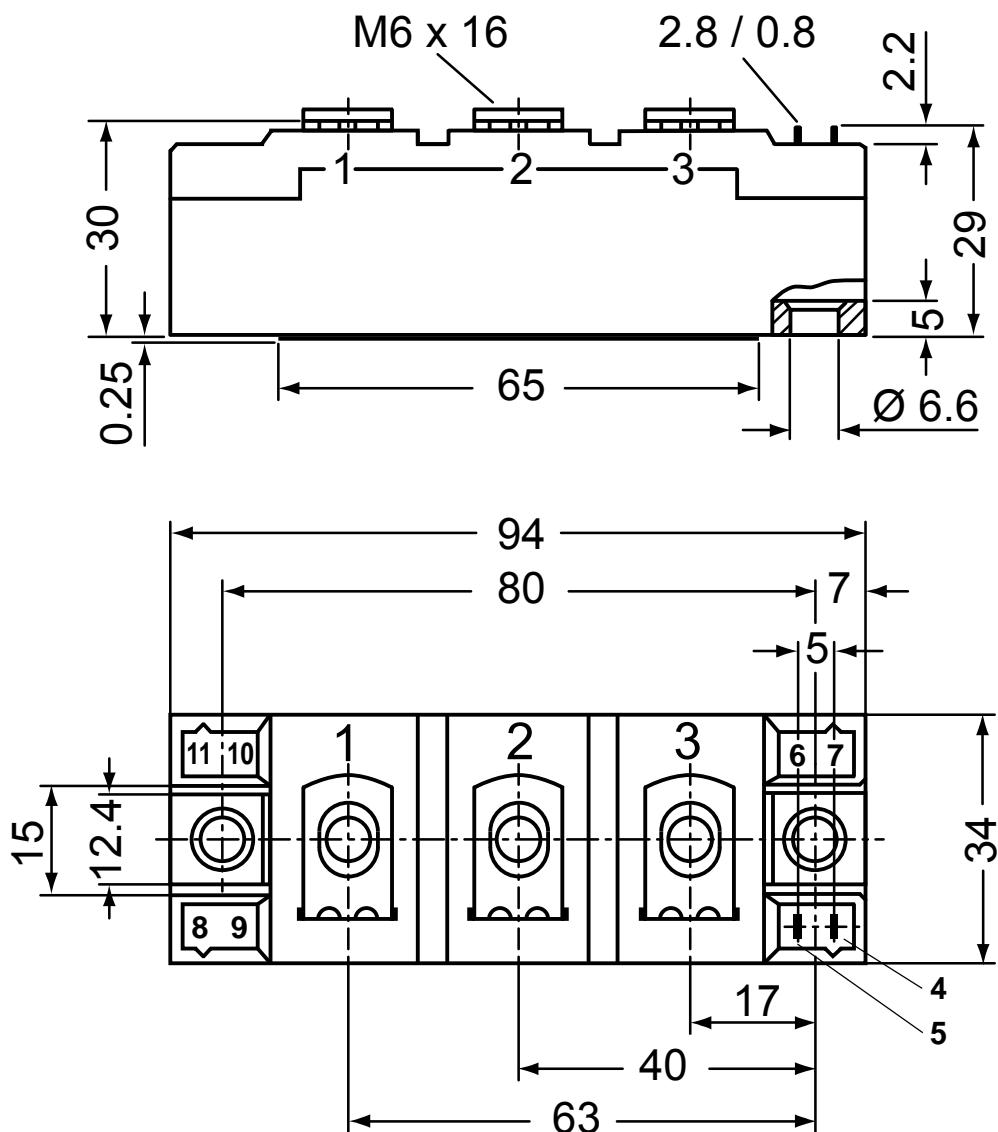
Equivalent Circuits for Simulation

* on die level

$T_{VJ} = 125$ °C

	Thyristor
V_0	threshold voltage
$R_{0\max}$	slope resistance * 0.8 $\text{m}\Omega$

Outlines Y4

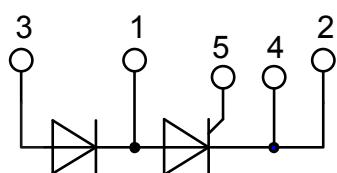


Optional accessories for modules

Keyed gate/cathode twin plugs with wire length = 350 mm, gate = white, cathode = red

Type ZY 180L (L = Left for pin pair 4/5) }

Type ZY 180R (R = Right for pin pair 6/7) } UL 758, style 3751



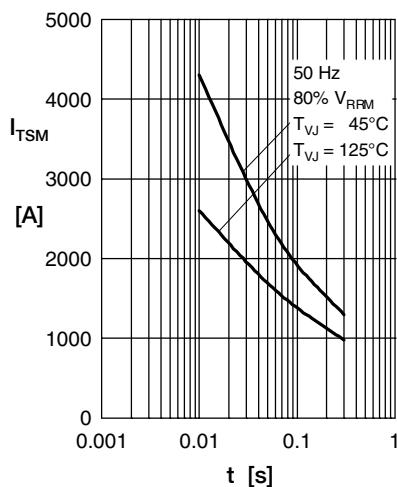
Thyristor

Fig. 1 Surge overload current I_{TSM} ,
 I_{FSM} : Crest value, t : duration

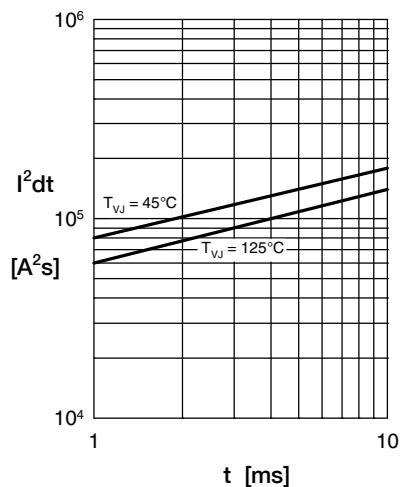


Fig. 2 I^2t versus time (1-10 ms)

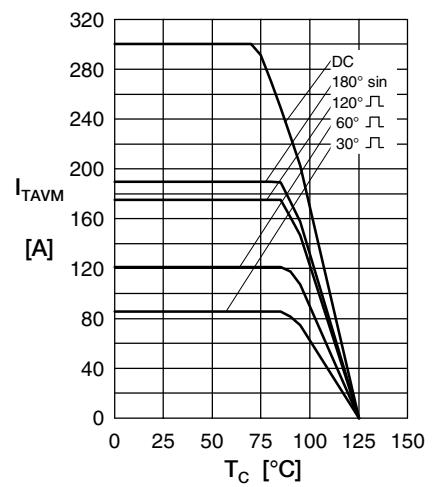


Fig. 3 Max. forward current
at case temperature

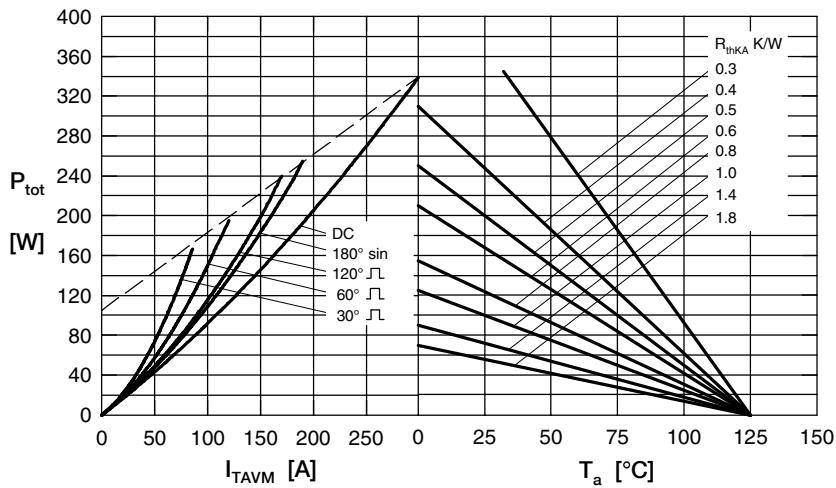


Fig. 4 Power dissipation vs. on-state current & ambient temperature
(per thyristor or diode)

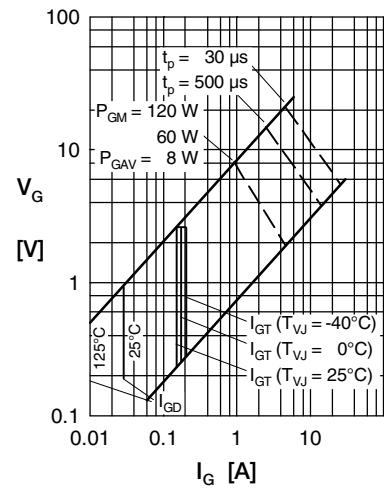


Fig. 5 Gate trigger characteristics

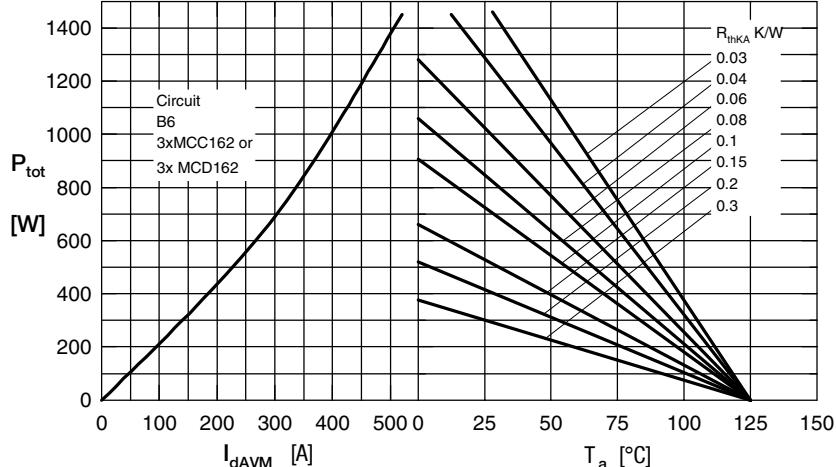


Fig. 6 Three phase rectifier bridge: Power dissipation versus direct output current and ambient temperature

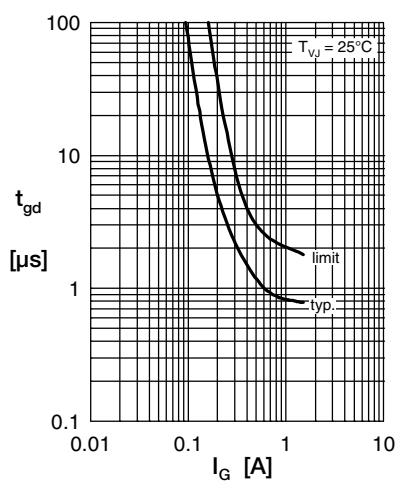


Fig. 7 Gate trigger delay time

Rectifier

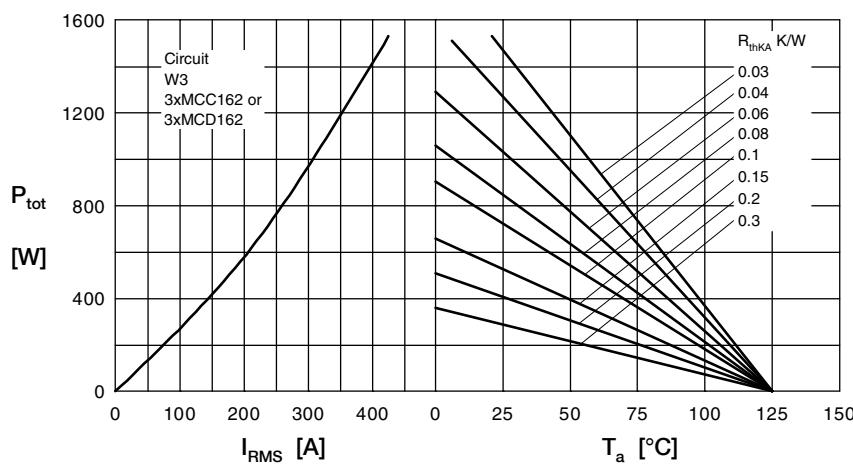


Fig. 8 Three phase AC-controller: Power dissipation versus RMS output current and ambient temperature

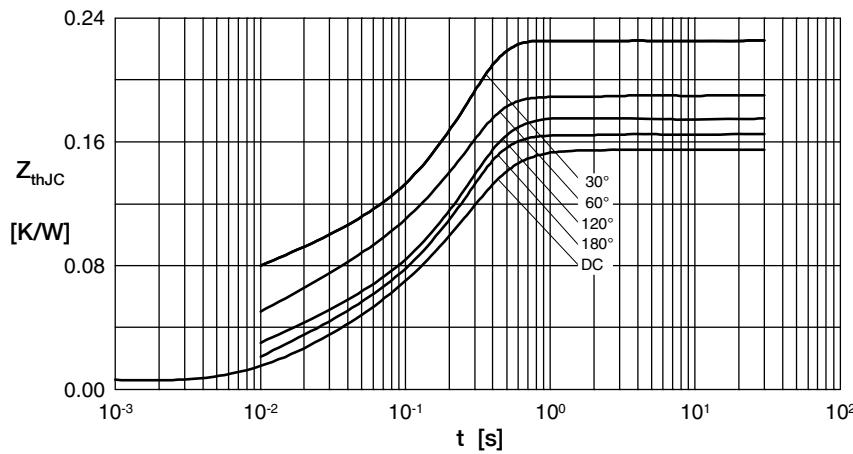


Fig. 9 Transient thermal impedance junction to case (per thyristor/diode)

R_{thJC} for various conduction angles d:

d	R_{thJC} [K/W]
DC	0.155
180°	0.167
120°	0.176
60°	0.197
30°	0.227

Constants for Z_{thJC} calculation:

i	R_{thi} [K/W]	t_i [s]
1	0.0072	0.001
2	0.0188	0.080
3	0.1290	0.200

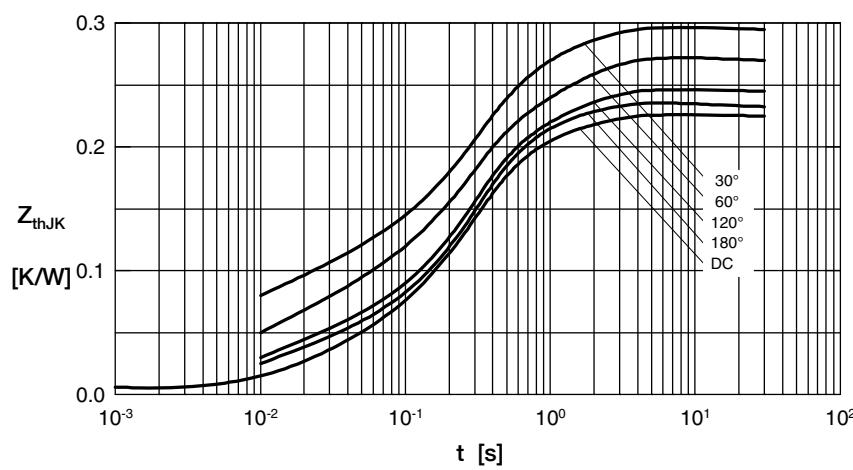


Fig. 10 Transient thermal impedance junction to heatsink (per thyristor/diode)

R_{thJK} for various conduction angles d:

d	R_{thJK} [K/W]
DC	0.225
180°	0.237
120°	0.246
60°	0.267
30°	0.297

Constants for Z_{thJK} calculation:

i	R_{thi} [K/W]	t_i [s]
1	0.0072	0.001
2	0.0188	0.080
3	0.1290	0.200
4	0.0700	1.000